

Category		Small and Medium Batches Order (Order area $\geq 10m^2$)	Prototype Order (Order area $< 3m^2$)
Product structure		1+n+1; 1+1+n+1+1; 2+n+2	1+n+1, 1+1+n+1+1, 2+n+2
		F+R, cu+F+cu, R+F+R+F+R, R+F+R	F+R, cu+F+cu, R+F+R+F+R, R+F+R
Number of layers	Rigid-flex PCB	$\leq 18L$	$\leq 24L$
	FPC	$\leq 10L$	$\leq 16L$
Board thickness (mm)	Rigid-flex board	0.3-3.2	0.3-3.2
	FPC	0.06-0.35	0.06-0.35
Board size (mm)	Rigid-flex PCB	15*15 to 310*510	15*15 to 310*510
	FPC	5*15 to 310*510	5*15 to 310*510
Copper thickness (OZ)	Maximum copper thickness of FR-4	Outer layer 2OZ, inner layer 2OZ	Outer layer 2OZ, inner layer 2OZ
	Maximum copper thickness of FPC	Outer layer 1 OZ, inner layer 1 OZ	Outer layer 2 OZ, inner layer 2 OZ
Minimum copper trace width and spacing capability (μm)		75/75	75/75
Minimum diameter of mechanical drill (mm)		0.2	0.15
Rigid part material	Tg170	S1000-2M,IT180A	S1000-2M,IT180A
	High TG halogen-free	S1165	S1165
	Thickness of dielectric layer (mm)	0.1-3.2	0.075-3.2
Flex part material	Flexible material	PI DuPont, Panasonic, Shengyi	PI DuPont, Panasonic, Shengyi
	Surface insulation layer	Cover film, soldermask	Cover film, soldermask
	Thickness of dielectric layer (mm)	0.025-0.1	0.012-0.1
Surface treatment	Rigid-flex board	HASL with lead / lead-free, immersion gold, immersion tin, immersion silver, OSP, HASL + gold finger, immersion gold + gold finger, nickel palladium gold, OSP + gold finger, immersion gold + OSP	HASL with lead / lead-free, immersion gold, immersion tin, immersion silver, OSP, HASL + gold finger, immersion gold + gold finger, nickel palladium gold, OSP + gold finger, immersion gold + OSP
	FPC	FPC	HASL with lead / lead-free, immersion gold, OSP